

ABSTRACT OF THE DISCLOSURE

In a semiconductor package including at least one
5 plate-like mount, a semiconductor chip has at least one
electrode formed on a top surface thereof, and is mounted
on the plate-like mount such that a bottom surface of the
semiconductor chip is in contact with the plate-like mount.
The semiconductor package also includes at least one lead
10 element having an outer portion arranged to be flush with
the plate-like mount, and an inner portion deformed and
shaped to overhang the semiconductor chip such that an inner
end of the lead element is spaced apart from the top surface
of the semiconductor chip. The semiconductor package
15 further includes a bonding-wire element bonded at ends
thereof to the electrode of the semiconductor chip and the
inner end of the lead element, an envelope sealing and
encapsulating the plate-like mount, the semiconductor chip,
the inner portion of the lead element, and the bonding-wire
20 element.